

Dual N-Channel MOSFET

General Description

The WSP8814 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSP8814 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

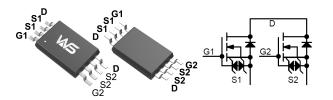
Product Summery

BVDSS	RDSON	ID
20V	9.5mΩ	9A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- ESD:2KV

TSSOP-8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	20	V	
V_{GS}	Gate-Source Voltage	±12	V	
I _D @T _c =25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹ 9		А	
I _D @T _c =70℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	7.5	А	
I _{DM}	Pulsed Drain Current ²	36	Α	
P _D @T _A =25°C	Total Power Dissipation ³	1.25	W	
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$	
T_J	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹		100	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		70	°C/W	





Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25 $^{\circ}\mathrm{C}$, ID=1mA		0.022		V/°C
	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =9A		7.6	9.5	mΩ
R _{DS(ON)}		V_{GS} =2.5 V , I_D =5 A		9.5	13	
V _{GS(th)}	Gate Threshold Voltage	., .,	0.5	0.75	1.2	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-2.33		mV/℃
-	Drain-Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =25℃			1	
I _{DSS}		V _{DS} =16V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 12V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		35		S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.5		Ω
Qg	Total Gate Charge (4.5V)			27		
Q _{gs}	Gate-Source Charge	V _{DS} =10V , V _{GS} =4.5V , I _D =9A		2.5		nC
Q_gd	Gate-Drain Charge			11.8		
T _{d(on)}	Turn-On Delay Time			13	24	
T _r	Rise Time	V_{DD} =10V , V_{GEN} =10V , R_{G} =6 Ω		16	28.5	
T _{d(off)}	Turn-Off Delay Time	$I_D=1A$,RL=10 Ω		40	75	ns
T _f	Fall Time			6	11	
C _{iss}	Input Capacitance			2000		
C _{oss}	Output Capacitance	V _{DS} =10V , V _{GS} =0V , f=1MHz		370		pF
C _{rss}	Reverse Transfer Capacitance			350		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,4}	V_G = V_D = $0V$, Force Current			2	Α
I _{SM}	Pulsed Source Current ^{2,4}				36	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_S =2A , T_J =25 $^{\circ}$ C			1.3	V
t _{rr}	Reverse Recovery Time	lF=5.5A,dI/dt=100A/μs , T _J =25℃		36.5		nS
Q _{rr}	Reverse Recovery Charge			30		nC

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t≦10sec.
- 2.The data tested by pulsed , pulse width \le 300us , duty cycle \le 2% 3.The power dissipation is limited by 150 $^{\circ}$ C junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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Typical Characteristics

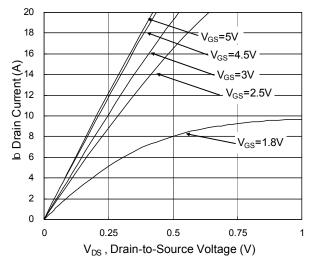


Fig.1 Typical Output Characteristics

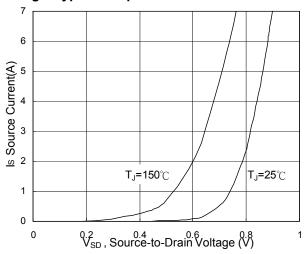


Fig.3 Forward Characteristics Of Reverse

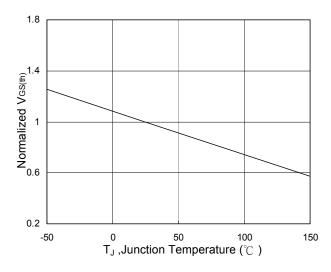


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

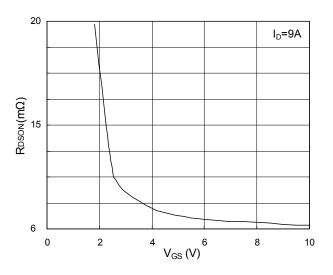


Fig.2 On-Resistance vs. Gate-Source

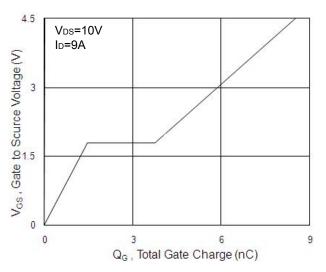


Fig.4 Gate-Charge Characteristics

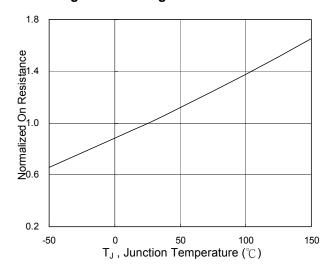
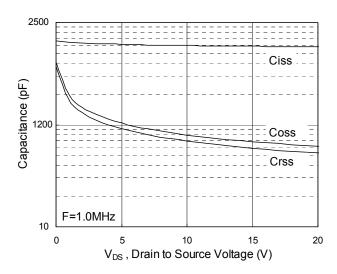


Fig.6 Normalized R_{DSON} vs. T_J



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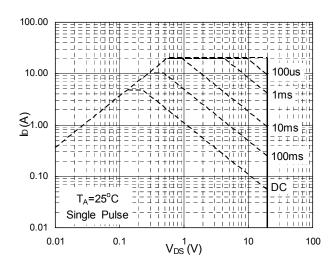


Fig.7 Capacitance

Fig.8 Safe Operating Area

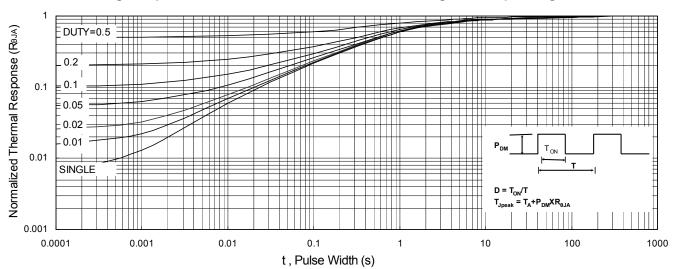


Fig.9 Normalized Maximum Transient Thermal Impedance

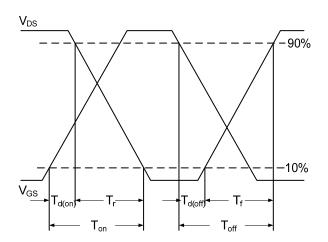


Fig.10 Switching Time Waveform

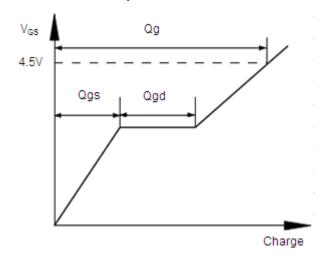


Fig.11 Gate Charge Waveform



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